

Press Release

New Inline X-ray System X7056-II BO for High-Throughput Wire Bond Inspection

Hanover, 10/05/2020 – **The role of power electronics is becoming increasingly critical in the automotive sector, especially for electric drives. Smooth functioning and long service life for power electronics ensure the necessary product safety and also the intended energy efficiency of electric vehicles and hybrids. New sensors and cameras are also providing even better protection for vehicles during operation. The new Viscom X7056-II BO system, which inspects bond wires optically and radiographically in an inline system at maximum inspection depth, ensures comprehensive inspection of power semiconductors and encapsulated sensor elements alike.**

The new X7056-II BO inline system effectively combines optical wire bond control with X-ray inspection to reliably and precisely inspect wire bonds – even enclosed ones – and concealed solder joints beneath chips. The unique combination of AOI and AXI in a single system ensures high-throughput handling to meet the most stringent cycle time requirements at a maximum inspection depth.

Tapes and wires, whether thick or thin, are inspected, as is the soldering quality of the dies. The high-resolution sensor technology means the scope of inspection covers all bond points and wires, as well as open and concealed connection points, so that the quality of wire runs, dies and component layers, damage and position deviations as well as voids in surface soldering can be detected with absolute certainty. The standard library contains all relevant inspection patterns for die bonds, ball-wedge, wedge-wedge and security bonds for very effective inspection program generation.

Viscom's new bond inspection system offers an ideal solution for the increasing demand for X-ray inspection in the bond area. The system is designed to be used in the production of high-end electronics and is ideal for installation in final assembly for power electronics, circuits, sensor construction and packaging to ensure 100% quality control. The Viscom range is rounded off by powerful verification and evaluation of statistical process control.



About Viscom

Founded in 1984, Viscom AG is one of the leading suppliers worldwide in the field of assembly inspection within electronics production. With its headquarters and production site in Hanover, Germany, the company develops, produces and sells high-quality inspection systems from the areas of AOI, SPI, AXI, MXI, bond inspection as well as CCI for protective coating inspection. The systems from Hanover set high standards in terms of accuracy and speed. The product range covers the complete spectrum of optical inspection and X-ray inspection for small- and medium-sized companies as well as for large series production. Viscom systems are used for 100% automatic inspection of electronic assemblies such as in the production of automotive electronics, aerospace technology or in the manufacture of telecommunications electronics.

Product development also focuses on customer-specific system developments and networking with other production processes for smart factory applications. In order to achieve this, Viscom AG increasingly invests in its own software and hardware development, which is constantly defining new standards in inspection technology.

International sales are handled by a broad network of its own subsidiaries, application centers, service centers and representatives. A service team of in-house technicians and application specialists commission Viscom systems worldwide, offering maintenance, conversion and modernization from a single source. In addition, system-specific training courses are offered for customers' operators, programmers and maintenance personnel. Experienced engineers and technicians from the application and service departments share their expert knowledge with participants.

Viscom AG has been listed on the Frankfurt Stock Exchange since 2006 (ISIN: DE0007846867).